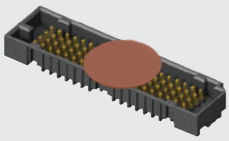
samtec

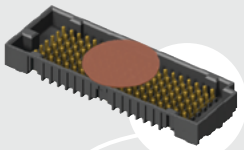
LP ARRAY™

(1.27 mm) .050"

LPAM–20–01.5–L–04–2–K



LPAM–20–01.5–L–06–2–K



LPAM SERIES

HIGH-SPEED LOW-PROFILE OPEN-PIN-FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?LPAM

Insulator Material:
Black LCP
Terminal Material:
Copper Alloy
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating:
2.3 A per pin
(8 adjacent pins powered)
Working Voltage:
250 VAC
RoHS Compliant:
Yes
Lead-Free Solderable:
Yes

RECOGNITIONS

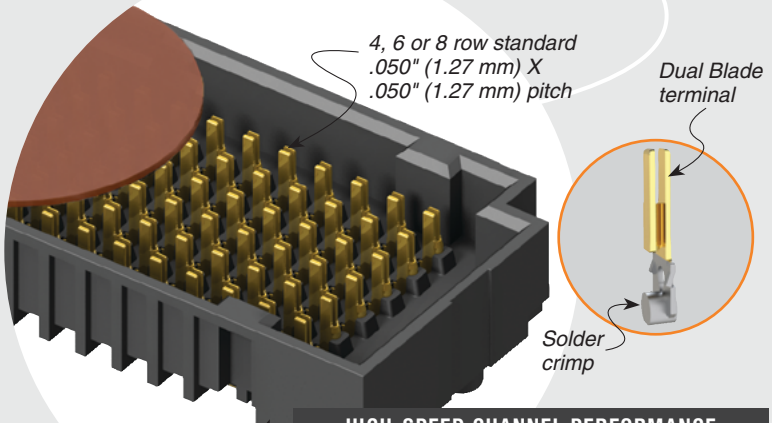
For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

Mates with:
LPAF
Standoffs:
JSO, SO

POWER/SIGNAL APPLICATION

Compatible with UMPT/UMPS for flexible two-piece power/signal solutions



HIGH-SPEED CHANNEL PERFORMANCE

LPAM/LPAF @ 5 mm Mated Stack Height
Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

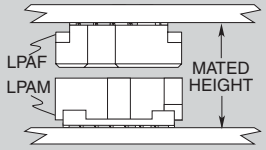
PAM4 56 Gbps

ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
- Other pins/row and row counts
- Other Gold plating options

LPAM	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	K	TR
	–10, –20, –30, –40, –50 (–08 rows only)	–01.0 = (1.0 mm) .039" –01.5 = (1.5 mm) .060"	–L = 10 µ" (0.25 µm) Gold on contact area, Matte Tin on solder tail	–04 = Four Rows –06 = Six Rows –08 = Eight Rows	–2 = Lead-Free Solder Crimp	–K = Polyimide film Pick & Place Pad	–TR = Tape & Reel

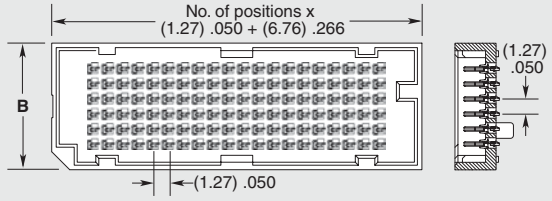
MATED HEIGHT

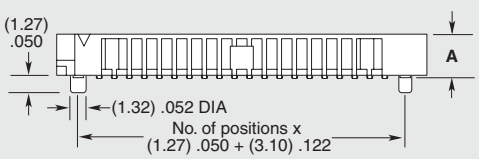


MATED HEIGHT*		
LPAM LEAD STYLE	LPAF LEAD STYLE –03.0	LPAF LEAD STYLE –03.5
–01.0	(4.00) .157	(4.50) .177
–01.5	(4.50) .177	(5.00) .197

*Processing conditions will affect mated height.

NO. OF ROWS	B
–04	(8.18) .322
–06	(10.72) .422
–08	(13.26) .522





LEAD STYLE	A
–01.0	(3.68) .145
–01.5	(4.19) .165

Notes:
Patent Pending

Some sizes, styles and options are non-standard, non-returnable.